

TELECOM MAGNETICS SM75570

Features

- Designed for use Conexant SMART HSF FF2A
- SMT package
- Small size



ELECTRICAL SPECIFICATIONS AT 25°C

URNS RATIO (1-2) : (3-4)

1 : 2 ± 2%

OCL @100kHz, 1V (1-2)

40μH MIN

LEAKAGE INDUCTANCE @4MHz, 1V

8μH MAX

INTERWINDING CAPACITANCE @1MHz

10pF MAX

SRF

4.0MHz TYP

DCR (1-2)

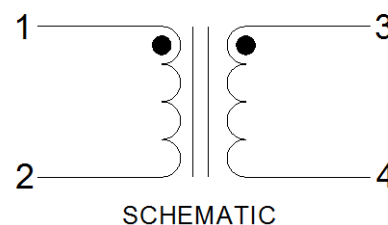
0.2Ω MAX

DCR (3-4)

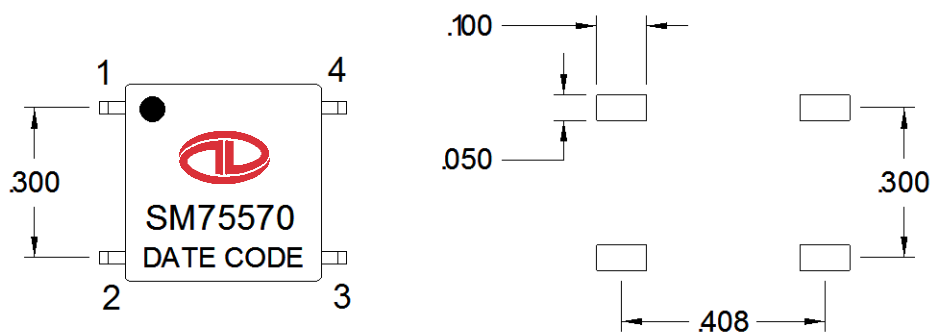
0.4Ω MAX

HIPOT PRIMARY & SECONDARY 1 MINUTE

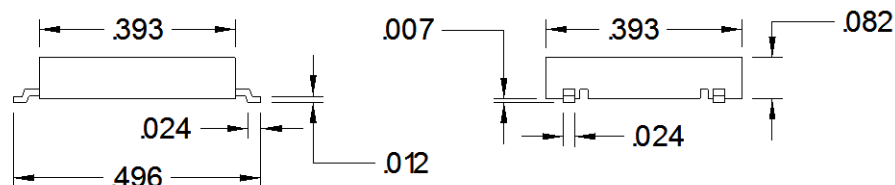
1500VRMS



OUTLINE DIMENSIONS



SUGGESTED PAD LAYOUT



Notes:

- All dimensions are in inches and typical unless otherwise specified.
- Coplanarity: ±.004
- For non-RoHS parts replace SM prefix with 42- (e.g. SM75570 becomes 42-75570)
- Terminal finish is compliant to RoHS requirements. Solder in accordance with J-STD-020C